

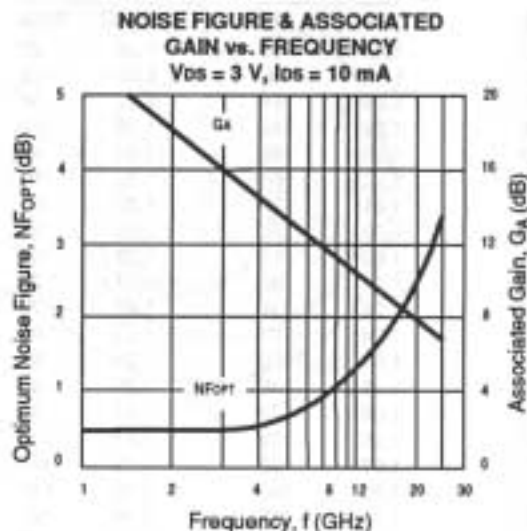
### FEATURES

- VERY HIGH  $f_{MAX}$ : 90 GHz
- LOW NOISE FIGURE
- HIGH ASSOCIATED GAIN
- $L_G = 0.3 \mu m$ ,  $W_G = 280 \mu m$
- N+ CONTACT LAYER (Triple Epitaxial Technology)
- PROVEN RELIABILITY AND STABILITY

### DESCRIPTION

The NE710 series features a low noise figure and high associated gain through K-band by employing a recessed 0.3 micron gate and triple epitaxial technology.

The device is available in chip form (NE71000). The surface of the device, except for the bonding pads, is passivated with SiO<sub>2</sub> and Si<sub>3</sub>N<sub>4</sub> for scratch protection as well as surface stabilization. The NE71083 is a low cost device for industrial applications, and the NE71084 is a low cost device for consumer applications.



### ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C)

PART NUMBER EIAJ <sup>1</sup> REGISTERED NUMBER PACKAGE OUTLINE			NE71000 CHIP			NE71083 25K406 83			NE71084 25K609 84		
SYMBOLS	PARAMETERS AND CONDITIONS	UNITS	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX
MAG	Maximum Available Gain <sup>2</sup> at V <sub>DS</sub> = 3 V, I <sub>DS</sub> = 20 mA, f = 4 GHz f = 8 GHz f = 12 GHz f = 18 GHz	dB dB dB dB		17.0 15.0 12.0 8.5				17.0 15.0 12.0 8.5			10.0
NF <sub>opt</sub>	Optimum Noise Figure <sup>3</sup> at V <sub>DS</sub> = 3 V, I <sub>DS</sub> = 10 mA, f = 4 GHz f = 8 GHz f = 12 GHz f = 18 GHz f = 25 GHz	dB dB dB dB dB		0.6 1.0 1.5 2.1 3.5	1.8		0.6 1.0 1.5 1.8	0.7 1.8		1.6	1.8
GA	Associated Gain at Optimum Noise Figure at V <sub>DS</sub> = 3 V, I <sub>DS</sub> = 10 mA, f = 4 GHz f = 8 GHz f = 12 GHz f = 18 GHz f = 25 GHz	dB dB dB dB dB	8.0	13.0 11.0 9.0 7.0 5.5		11.5 8.0	13.0 11.0 9.0		8.0	9.0	
P <sub>1dB</sub>	Output Power at 1 dB Compression Point at V <sub>DS</sub> = 3 V, I <sub>DS</sub> = 30 mA, f = 4 GHz f = 12 GHz	dBm dBm		14.5			14.5	14.5		14.5	

**Notes:**

1. Electronic Industrial Association of Japan.

2. Gain Calculations:

$$MAG = \frac{|S_{21}|}{|S_{12}|} \left( K \pm \sqrt{K^2 - 1} \right), \text{ When } K \leq 1, \text{ MAG is undefined and MSG values are used. } MSG = \frac{|S_{21}|}{|S_{12}|}, K = \frac{1 + |\Delta|^2 - |S_{11}|^2 - |S_{22}|^2}{2 |S_{12} S_{21}|}, \Delta = S_{11} S_{22} - S_{21} S_{12}$$

3. Typical values of noise figures are those obtained when 50% of the devices from a large number of lots were individually measured in a circuit with the input individually tuned to obtain the minimum value. Maximum values are criteria established on the production line as a "go-no-go" screening test with the fixture tuned for the "generic" type but not for each specimen.

**ELECTRICAL CHARACTERISTICS** (TA = 25°C)

PART NUMBER EIAJ <sup>1</sup> REGISTERED NUMBER PACKAGE OUTLINE			NE71000 CHIP			NE71083 2SK406 83			NE71084 2SK609 84		
SYMBOLS	PARAMETERS AND CONDITIONS	UNITS	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX
I <sub>DS</sub>	Saturated Drain Current at V <sub>DS</sub> = 3 V, V <sub>GS</sub> = 0	mA	20	40	120	20	40	120	20	40	120
V <sub>P</sub>	Pinch-off Voltage at V <sub>DS</sub> = 3 V, I <sub>DS</sub> = 0.1 mA	V	-0.5	-1.1	-3.5	-0.5	-1.1	-3.5	-0.5	-1.1	-3.5
g <sub>m</sub>	Transconductance at V <sub>DS</sub> = 3 V, I <sub>DS</sub> = 10 mA	mS	20	50	100	20	50	100	20	50	100
I <sub>GS</sub>	Gate to Source Leakage Current at V <sub>GS</sub> = -5 V	μA		1	10		1	10		1	10
R <sub>TH</sub> (CH-C)	Thermal Resistance (Channel to Case)	°C/W			190 <sup>2</sup>			450			450

Notes:

1. Electronic Industrial Association of Japan.
2. R<sub>TH</sub> for chip mounted on an infinite heat sink.

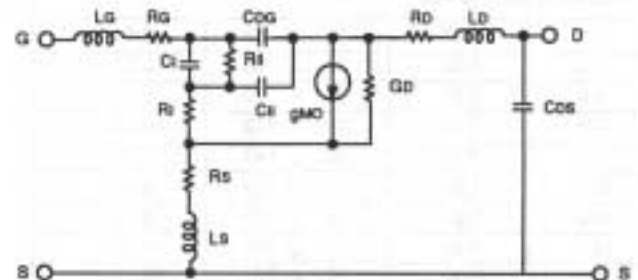
**ABSOLUTE MAXIMUM RATINGS<sup>1</sup>** (TA = 25°C)

SYMBOLS	PARAMETERS	UNITS	RATINGS
V <sub>DS</sub>	Drain to Source Voltage	V	5
V <sub>GS0</sub>	Gate to Source Voltage	V	-8
I <sub>DS</sub>	Drain Current	mA	120
P <sub>IN</sub>	RF Input Power	mW	40
T <sub>CH</sub>	Channel Temperature	°C	175
T <sub>STG</sub>	Storage Temperature	°C	-65 to +175
P <sub>T</sub>	Total Power Dissipation		
	NE71000	mW	400 <sup>2</sup>
	NE71083	mW	270
	NE71084	mW	270

Note:

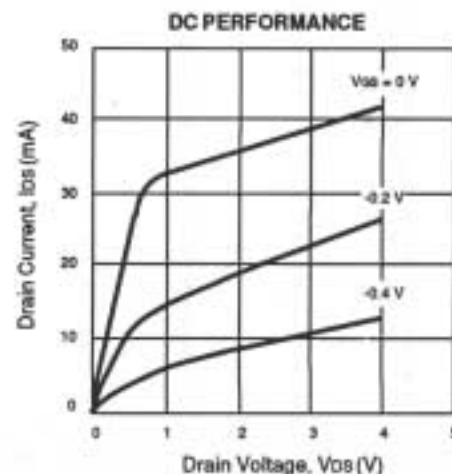
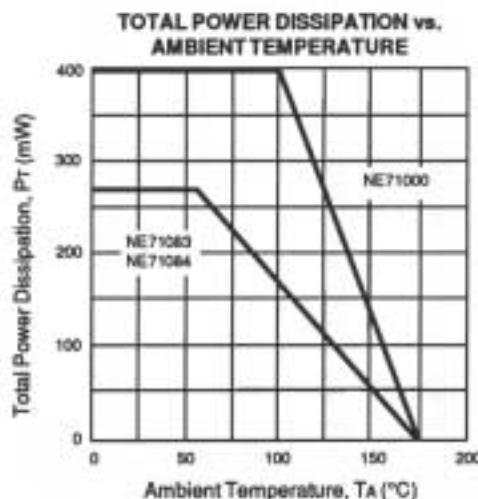
1. Operation in excess of any one of these parameters may result in permanent damage.
2. For chip mounted on a copper heat sink.

**EQUIVALENT CIRCUIT**



Components	Value
L <sub>g</sub>	0.005 nH
R <sub>g</sub>	2.00 Ω
C <sub>g</sub>	0.28 pF
R <sub>i</sub>	1.6 Ω
C <sub>i</sub>	0.064 pF
R <sub>b</sub>	1 M Ω
R <sub>s</sub>	1.5 Ω
L <sub>s</sub>	0.001 nH
C <sub>cd</sub>	0.0033 pF
R <sub>d</sub>	1.5 Ω
L <sub>d</sub>	0.005 nH
C <sub>os</sub>	0.03 pF
g <sub>MO</sub>	480 mS
G <sub>o</sub>	1.5 mS

**TYPICAL PERFORMANCE CURVES** (TA = 25 °C)



## NE710 SERIES

### TYPICAL NOISE PARAMETERS

#### NE71000

FREQ. (GHz)	NF <sub>MIN</sub> (dB)	Γ <sub>OPT</sub>		R <sub>n</sub> /50 Ω
		MAG	ANG	
V <sub>DS</sub> = 3 V, I <sub>DS</sub> = 10 mA				
1.0	0.50	.90	∠ 12	0.57
2.0	0.55	.85	∠ 21	0.51
4.0	0.60	.75	∠ 40	0.44
6.0	0.80	.69	∠ 55	0.38
8.0	1.00	.62	∠ 70	0.33
10.0	1.30	.56	∠ 85	0.28
12.0	1.60	.52	∠ 99	0.24
14.0	1.90	.49	∠ 114	0.20
16.0	2.20	.47	∠ 127	0.18
18.0	2.50	.45	∠ 140	0.16

#### NE71083

FREQ. (GHz)	NF <sub>MIN</sub> (dB)	Γ <sub>OPT</sub>		R <sub>n</sub> /50 Ω
		MAG	ANG	
V <sub>DS</sub> = 3 V, I <sub>DS</sub> = 10 mA				
1.0	0.45	.90	∠ 17	0.65
2.0	0.55	.84	∠ 40	0.57
4.0	0.60	.72	∠ 79	0.48
6.0	0.80	.62	∠ 112	0.39
8.0	1.00	.56	∠ 143	0.33
10.0	1.35	.50	∠ 168	0.28
12.0	1.60	.46	∠ -165	0.24
14.0	1.90	.43	∠ -140	0.20
16.0	2.10	.40	∠ -112	0.18
18.0	2.70	.40	∠ -84	0.16

### TYPICAL NOISE PARAMETERS

#### NE71084

FREQ. (GHz)	NF <sub>MIN</sub> (dB)	Γ <sub>OPT</sub>		R <sub>n</sub> /50 Ω
		MAG	ANG	
V <sub>DS</sub> = 3 V, I <sub>DS</sub> = 10 mA				
1.0	0.50	.90	∠ 17	0.50
2.0	0.55	.85	∠ 37	0.47
4.0	0.60	.71	∠ 85	0.43
6.0	0.80	.61	∠ 127	0.35
8.0	1.00	.54	∠ 165	0.30
10.0	1.30	.52	∠ -158	0.25
12.0	1.60	.51	∠ -124	0.20